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Aqueous system curable resin composition and method of
forming a film or multilayer films using same
Abstract

To provide an aqueous system curable resin composition excellent in film forming ability in a low temperature and/or
5 high humidity environment, in adhesion to substrates and in adhesion to topcoats when topcoating is carried out, as well as a method of forming a film or multilayer films using the composition.

An aqueous system curable resin composition, wherein an
10 epoxy resin (A) and a self-emulsifiable polyisocyanate resin (B) are dispersed in an aqueous system.

A method of forming a film by applying a curable resin composition to substrates, wherein the curable resin composition is the above aqueous system curable resin
15 composition.

Further, a method of forming multilayer films by applying a curable resin composition to substrates, followed by applying a topcoating composition, wherein the curable resin composition is the above aqueous system curable resin composition.